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(74) Agents: **HAUSER, Robert, Scott** et al.; 7005 Southfront Road, Livermore, California 94551 (US).

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(71) Applicant (for all designated States except US): **FORM-FACTOR, INC.** [US/US]; 7005 Southfront Road, Livermore, California 94551 (US).

(72) Inventor; and

(75) Inventor/Applicant (for US only): **KIM, Tae, Ma** [US/US]; 6047 Kingsmill Drive, Dublin, California 94568 (US).

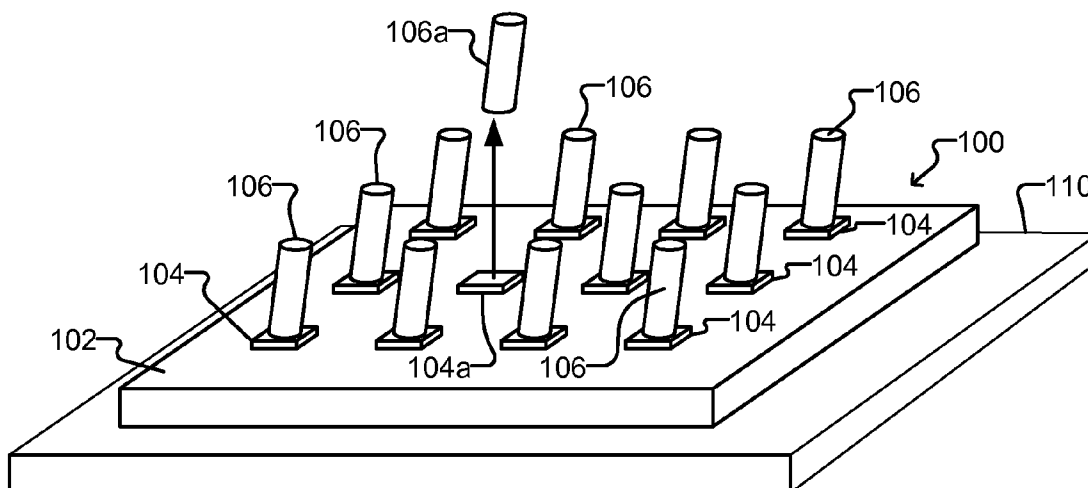
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(54) Title: ATTACHMENT OF AN ELECTRICAL ELEMENT TO AN ELECTRONIC DEVICE USING A CONDUCTIVE MATERIAL



(57) Abstract: An electrical element can be attached and electrically connected to a substrate by a conductive adhesive material. The conductive adhesive material can electrically connect the electrical element to a terminal or other electrical conductor on the substrate. The conductive adhesive material can be cured by directing a flow of heated gas onto the material or by heating the material through a support structure on which the substrate is located. A non-conductive adhesive material can attach the electrical element to the substrate with a greater adhesive strength than the conductive adhesive. The non-conductive adhesive material can also be cured by directing a flow of heated gas onto the material or by heating the material through the support structure on which the substrate is located. The non-conductive adhesive material can cover the conductive adhesive material.

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